

In the Claims

This listing of claims will replace all prior versions, and listings, of claims.

Listing of Claims

1. (Currently Amended): A reliability assessment system for assessing a reliability of a semiconductor product, comprising:
an interface to receive a selection of an assessment item for the semiconductor product, and input items corresponding to the assessment item, wherein the assessment item comprises a manufacturing process for the semiconductor product; and
an assessment engine to perform a reliability assessment for the semiconductor product toward the assessment item accordingly to the input items and the manufacturing process, generate a result of the reliability assessment, and display the result on the interface, wherein the result comprises at least one output item corresponding to the assessment item.
2. (Original): The system of claim 1 wherein the interface is a web-based interface.
3. (Original): The system of claim 1 wherein the assessment engine further writes the input items and the corresponding result to a database.
4. (Original): The system of claim 1 further comprising an email server.

5-7. (Cancelled).

8. (Currently Amended): The system of claim 7 wherein the process comprises GOI (gate oxide integrity), HCI (hot carrier injection), NBTI (negative bias temperature instability), EM (electromigration) or IMD(intermetal dielectirc)-TDDB (time dependent dielectric breakdown).

9-10. (Cancelled).

11. (Currently Amended): The system of claim 9 1 wherein the assessment item comprises EFR (early failure rate), LTFR (long term failure rate), overdrive, overshoot, or temperature of the semiconductor product.

12. (Currently Amended): The system of claim 1 wherein the input items comprise technology and specifications of a the semiconductor product.

13. (Cancelled).

14. (Currently Amended): The system of claim 13 12 wherein the technology is geometry of the semiconductor product.

15. (Currently Amended): The system of claim 13 12 wherein the specification comprises parameters comprising at least a voltage and a lifetime of the semiconductor product.

16. (Currently Amended): A computerized reliability assessment method for assessing a reliability of a semiconductor product, comprising the steps of:
receiving a selection of an assessment item for the semiconductor product, and
input items corresponding to the assessment item through a web-based interface, wherein the assessment item comprises a manufacturing process for the semiconductor product;
performing a reliability assessment for the semiconductor product toward the assessment item accordingly to the input items and the manufacturing process; and
generating a result of the reliability assessment, wherein the result comprises at least one output item corresponding to the assessment item.

17. (Original): The method of claim 16 further comprising displaying the result on the web-based interface.

18. (Original): The method of claim 16 further comprising writing the input items and the corresponding result to a database.

19. (Original): The method of claim 16 further comprising sending an email notification.

20-22. (Cancelled).

23. (Currently Amended): The method of claim 22 wherein the process comprises GOI (gate oxide integrity), HCI (hot carrier injection), NBTI (negative bias temperature instability), EM (electromigration) or IMD(intermetal dielectirc)-TDDB (time dependent dielectric breakdown).

24-25. (Cancelled).

26. (Currently Amended): The method of claim 24 16 wherein the assessment item comprises EFR (early failure rate), LTFR (long term failure rate), overdrive, overshoot, or temperature of the semiconductor product.

27. (Currently Amended): The method of claim 16 wherein the input items comprise technology and specifications of a the semiconductor product.

28. (Cancelled).

29. (Currently Amended): The method of claim 28 27 wherein the technology is geometry of the semiconductor product.

30. (Currently Amended): The method of claim 28 27 wherein the specification comprises parameters comprising at least a voltage and a lifetime of the semiconductor product.

31. (Currently Amended): A machine-readable storage medium storing a computer program which, when executed, directs a computer to perform a method of reliability assessment for assessing a reliability of a semiconductor product, comprising the steps of:

receiving a selection of an assessment item for the semiconductor product, and

input items corresponding to the assessment item through a web-based interface, wherein the assessment item comprises a manufacturing process for the semiconductor product;

performing a reliability assessment for the semiconductor product toward the assessment item accordingly to the input items and the manufacturing process; and

generating a result of the reliability assessment, wherein the result comprises at least one output item corresponding to the assessment item.

32. (Currently Amended): The storage medium of claim 31 wherein the method further comprising comprises displaying the result on the web-based interface.

33. (Currently Amended): The storage medium of claim 31 wherein the method further ~~comprising~~ comprises writing the input items and the corresponding result to a database.

34. (Currently Amended): The storage medium of claim 31 wherein the method further ~~comprising~~ comprises sending an email notification.

35-37. (Cancelled).

38. (Currently Amended): The storage medium of claim 37 wherein the process comprises GOI (gate oxide integrity), HCl (hot carrier injection), NBTI (negative bias temperature instability), EM (electromigration) or IMD(intermetal dielectirc)-TDDB (time dependent dielectric breakdown).

39-40. (Cancelled).

41. (Currently Amended): The storage medium of claim 39 31 wherein the assessment item comprises EFR (early failure rate), LTFR (long term failure rate), overdrive, overshoot, or temperature of the semiconductor product.

42. (Currently Amended): The storage medium of claim 31 wherein the input items comprise technology and specifications of a the semiconductor product.

43. (Cancelled).

44. (Currently Amended): The storage medium of claim 43 42 wherein the technology is geometry of the semiconductor product.

45. (Currently Amended): The storage medium of claim 43 42 wherein the specification comprises parameters further comprising at least a voltage and a lifetime of the semiconductor product.

46-52. (Cancelled).

53. (Currently Amended): A set of application program interfaces embodied on a computer-readable medium for execution on a computer in conjunction with an application program that performs a reliability assessment for assessing a reliability of a semiconductor product, comprising:

a first interface to receive a selection of an assessment item for the semiconductor product, and input items corresponding to the assessment item of a reliability inquiry; and

a second interface to display a result of the reliability assessment, in which the result comprises at least one output item corresponding to the assessment item, and the result is generated accordingly to a reliability assessment for the semiconductor product toward the assessment item based on the input items and the manufacturing process.

54-55. (Cancelled).